

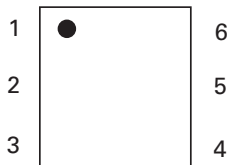
RoHS Battrax® Single Port Positive/Negative - MS-013



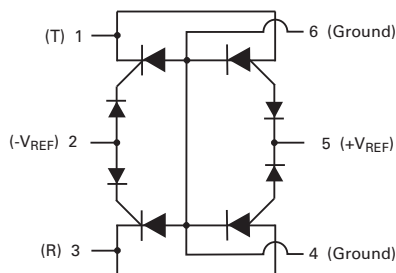
Agency Approvals

Agency	Agency File Number
	E133083

Pinout Designation



Schematic Symbol



Electrical Characteristics

Part Number	Marking	V_{DRM} @ $I_{DRM}=5\mu A$	V_S @ $100V/\mu s$	I_H	I_S	I_T	V_T @ $I_T=2.2$ Amps	Capacitance*	
		V min	V max	mA min	mA max	A max	V max	pF min	pF max
B3104UCLxx	B3104UC	$ \pm V_{REF} + \pm 1.2V $	$ \pm V_{REF} + \pm 10V $	100	100	2.2	4	30	200
B3164UCLxx	B3164UC	$ \pm V_{REF} + \pm 1.2V $	$ \pm V_{REF} + \pm 10V $	160	100	2.2	4	30	200
B3204UCLxx	B3204UC	$ \pm V_{REF} + \pm 1.2V $	$ \pm V_{REF} + \pm 10V $	200	100	2.2	4	30	200

Notes:

- Absolute maximum ratings measured at $T_A = 25^\circ C$ (unless otherwise noted).
- Devices are bi-directional
- All electrical characteristics shown are defined from Tip (pin 1) to Ground (pin 4 & 6) and Ring (pin 3) to Ground (pin 4 & 6)

- V_{REF} Max Value for the negative Battrax is -200 V.
- V_{REF} Max Value for the positive Battrax is +110 V.
- **XX** = Part Number Suffix: **TP** (Tube Pack) or **RP** (Reel Pack).

* Off-state capacitance (C_O) is measured across pins 1 & 4,6 and 3 & 4,6 at 1 MHz with a 2V bias.

Description

The Single Port Positive/Negative Battrax Series are programmable SIDACTor® devices designed to protect SLICs (Subscriber Line Interface Circuit) from damaging overvoltage transients.

This series is designed specifically to protect SLIC devices utilizing positive and negative ringing signals. This one device will protect a single port.

Features and Benefits

- Low voltage overshoot
- Low on-state voltage
- Does not degrade with use
- Fails short circuit when surged in excess of ratings
- Low Capacitance
- Positive and negative ringing compatible
- Single-port protect
- Gate trigger tracking device

Applicable Global Standards

- TIA-968-A
- ITU K.20/21 Enhanced Level
- ITU K.20/21 Basic Level
- GR 1089 Inter-building
- GR 1089 Intra-building
- IEC 61000-4-5
- YD/T 1082
- YD/T 993
- YD/T 950

Surge Ratings

Series	I_{PP}										I_{TSM} 50/60 Hz	di/dt
	0.2x310 ¹ 0.5x700 ²	2x10 ¹ 2x10 ²	8x20 ¹ 1.2x50 ²	10x160 ¹ 10x160 ²	10x560 ¹ 10x560 ²	5x320 ¹ 9x720 ²	10x360 ¹ 10x360 ²	10x1000 ¹ 10x1000 ²	5x310 ¹ 10x700 ²			
	A min	A min	A min	A min	A min	A min	A min	A min	A min	A min		
C	50	500	400	200	150	200	175	100	200	50		500

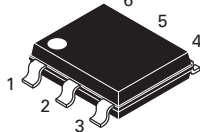
Notes:

- 1 Current waveform in μ s
2 Voltage waveform in μ s

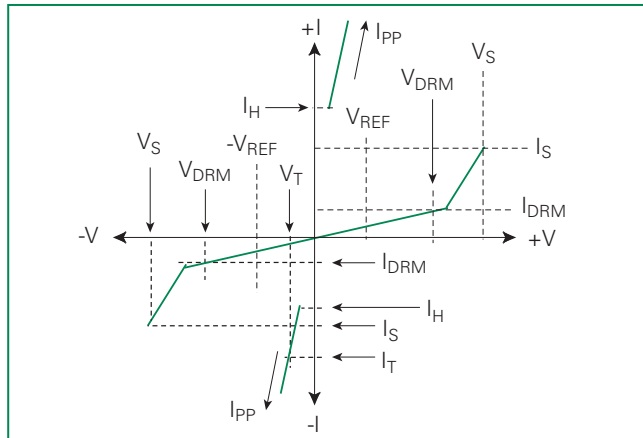
- Peak pulse current rating (I_{PP}) is repetitive and guaranteed for the life of the product.
- I_{PP} ratings applicable over temperature range of -40°C to +85°C (I_{PP} rating assumes V_{REF} equals +/- 48 V)
- The device must initially be in thermal equilibrium with -40°C $\leq T_J \leq$ +150°C

Thermal Considerations

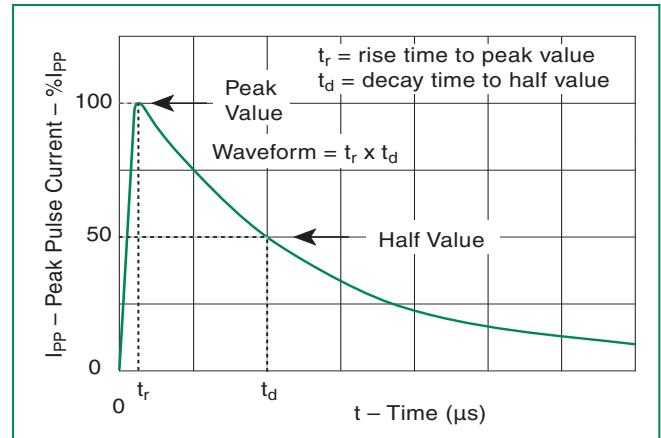
Package	Symbol	Parameter	Value	Unit
Modified MS-013 6	T_J	Operating Junction Temperature Range	-40 to +125	°C
	T_S	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	60	°C/W



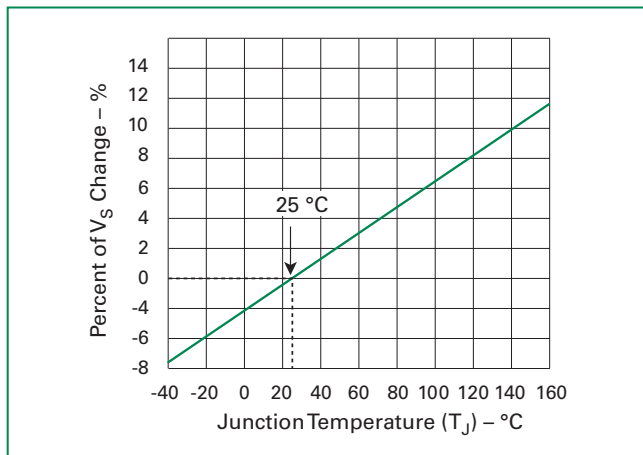
V-I Characteristics



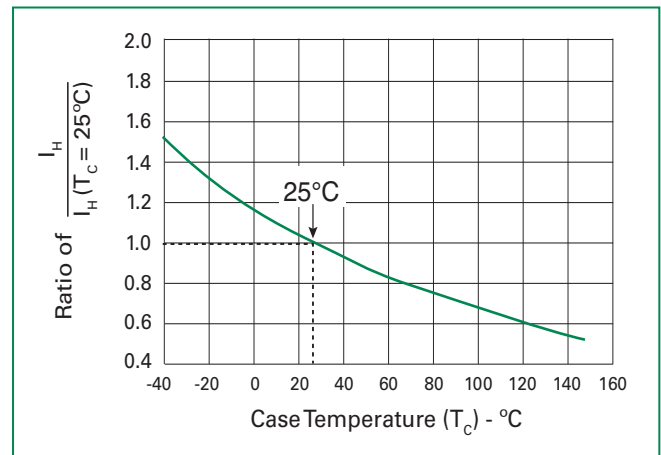
$t_r \times t_d$ Pulse Waveform



Normalized V_S Change vs. Junction Temperature

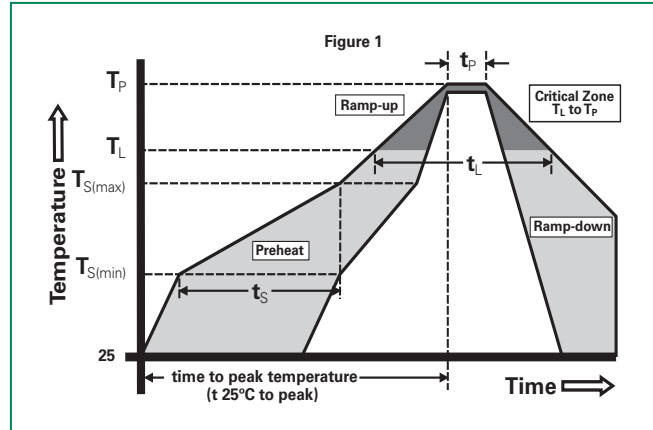


Normalized DC Holding Current vs. Case Temperature



Soldering Parameters

Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max ($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max.
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max.
Reflow	-Temperature (T_L) (Liquidus)	+217°C
	-Temperature (t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to Peak Temp (T_p)		8 min. Max.
Do not exceed		+260°C



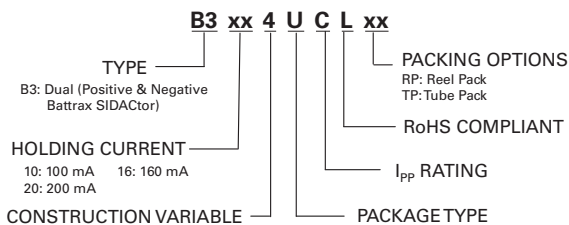
Physical Specifications

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL recognized epoxy meeting flammability classification 94V-0

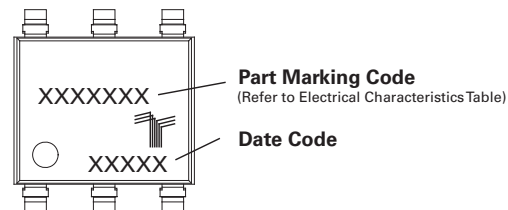
Environmental Specifications

High Temp Voltage Blocking	80% Rated V_{DRM} (V_{DC} Peak) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A-104
Biased Temp & Humidity	52 V_{DC} (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Autoclave (Pressure Cooker Test)	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

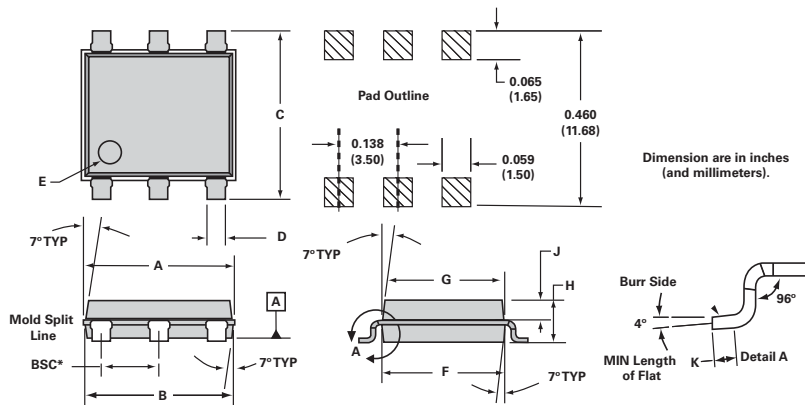
Part Numbering



Part Marking



Dimensions — MS-013



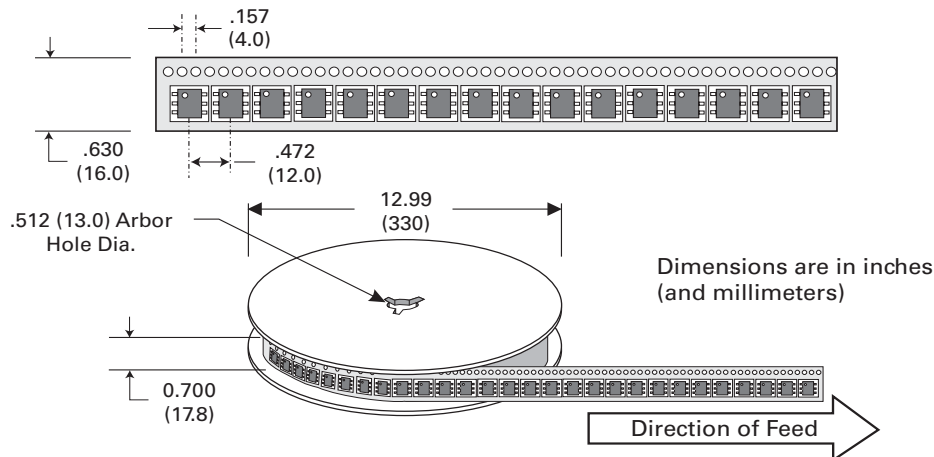
Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.360	0.364	9.14	9.25
B	0.352	0.356	8.94	9.04
C	0.400	0.412	10.16	10.46
D	0.043	0.045	1.09	1.13
E	0.047	0.055	1.19	1.40
F	0.293	0.297	7.44	7.54
G	0.289	0.293	7.34	7.44
H	0.089	0.093	2.26	2.36
J	0.041	0.049	1.04	1.24
K	0.020		0.51	
BSC*	0.133	0.143	3.38	3.63

* BSC = Basic Spacing between Centers

Packing Options

Package Type	Description	Quantity	Added Suffix	Industry Standard
U	Modified MS-013 6-pin Tape and Reel Pack	1500	RP	EIA-481-D
	Modified MS-013 6-pin Tube Pack	500 (50 per tube)	TP	N/A

Tape and Reel Specification — MS-013



Tube Pack Specification — MS-013

